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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: [info@chipsmall.com](mailto:info@chipsmall.com) Web: [www.chipsmall.com](http://www.chipsmall.com)

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# SPECIFICATION

(Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

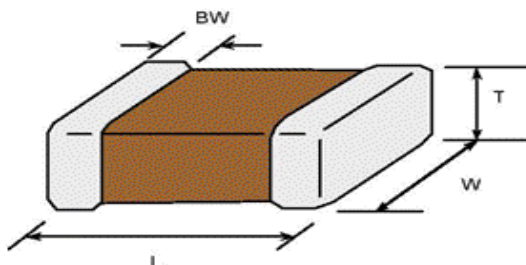
- Samsung P/N : **CL21B153KBANNNC**
- Description : **CAP, 15nF, 50V, ±10%, X7R, 0805**

## A. Samsung Part Number

**CL** **21** **B** **153** **K** **B** **A** **N** **N** **N** **C**  
① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

|                                |                                       |                          |  |                         |  |  |  |  |  |  |
|--------------------------------|---------------------------------------|--------------------------|--|-------------------------|--|--|--|--|--|--|
| ① <b>Series</b>                | Samsung Multi-layer Ceramic Capacitor |                          |  |                         |  |  |  |  |  |  |
| ② <b>Size</b>                  | 0805 (inch code)                      | L : 2.00 ± 0.10 mm       |  | W : 1.25 ± 0.10 mm      |  |  |  |  |  |  |
| ③ <b>Dielectric</b>            | X7R                                   | ⑧ <b>Inner electrode</b> |  | Ni                      |  |  |  |  |  |  |
| ④ <b>Capacitance</b>           | 15 nF                                 | ⑨ <b>Termination</b>     |  | Cu                      |  |  |  |  |  |  |
| ⑤ <b>Capacitance tolerance</b> | ±10 %                                 | ⑩ <b>Plating</b>         |  | Sn 100% (Pb Free)       |  |  |  |  |  |  |
| ⑥ <b>Rated Voltage</b>         | 50 V                                  | ⑪ <b>Product</b>         |  | Normal                  |  |  |  |  |  |  |
| ⑦ <b>Thickness</b>             | 0.65 ± 0.10 mm                        | ⑫ <b>Special</b>         |  | Reserved for future use |  |  |  |  |  |  |
|                                |                                       | ⑬ <b>Packaging</b>       |  | Cardboard Type, 7" reel |  |  |  |  |  |  |

## B. Structure & Dimension



| Samsung P/N     | Dimension(mm) |             |             |                |
|-----------------|---------------|-------------|-------------|----------------|
|                 | L             | W           | T           | BW             |
| CL21B153KBANNNC | 2.00 ± 0.10   | 1.25 ± 0.10 | 0.65 ± 0.10 | 0.50 +0.2/-0.3 |

### C. Samsung Reliability Test and Judgement Condition

|                                  | Judgement  | Test condition  |
|----------------------------------|--|---|
| Capacitance                      | Within specified tolerance   | 1kHz $\pm 10\%$ / 1.0 $\pm 0.2V_{rms}$  |
| Tan $\delta$ (DF)                | 0.025 max.   | *A capacitor prior to measuring the capacitance is heat treated at 150°C $\pm 10^\circ\text{C}$ for 1hour and maintained in ambient air for 24 $\pm 2$ hours.                 |
| Insulation Resistance            | 10,000Mohm or 500Mohm $\times \mu\text{F}$<br>Whichever is smaller   | Rated Voltage 60~120 sec.   |
| Appearance                       | No abnormal exterior appearance  | Microscope ( $\times 10$ )  |
| Withstanding Voltage             | No dielectric breakdown or mechanical breakdown  | 250% of the rated voltage   |
| Temperature Characteristics      | X7R<br>(From -55°C to 125°C, Capacitance change should be within $\pm 15\%$ )  |   |
| Adhesive Strength of Termination | No peeling shall be occur on the terminal electrode  | 500g-f, for 10 $\pm 1$ sec.   |
| Bending Strength                 | Capacitance change : within $\pm 12.5\%$   | Bending to the limit (1mm) with 1.0mm/sec.  |
| Solderability                    | More than 75% of terminal surface is to be soldered newly  | SnAg3.0Cu0.5 solder<br>245 $\pm 5^\circ\text{C}$ , 3 $\pm 0.3$ sec.<br>(preheating : 80~120°C for 10~30sec.)  |
| Resistance to Soldering Heat     | Capacitance change : within $\pm 7.5\%$<br>Tan $\delta$ , IR : initial spec.   | Solder pot : 270 $\pm 5^\circ\text{C}$ , 10 $\pm 1$ sec.  |
| Vibration Test                   | Capacitance change : within $\pm 5\%$<br>Tan $\delta$ , IR : initial spec.   | Amplitude : 1.5mm<br>From 10Hz to 55Hz (return : 1min.)<br>2hours $\times$ 3 direction (x, y, z)  |
| Moisture Resistance              | Capacitance change : within $\pm 12.5\%$<br>Tan $\delta$ : 0.05 max<br>IR : 500Mohm or 25Mohm $\times \mu\text{F}$<br>Whichever is smaller   | With rated voltage<br>40 $\pm 2^\circ\text{C}$ , 90~95%RH, 500+12/-0hrs   |
| High Temperature Resistance      | Capacitance change : within $\pm 12.5\%$<br>Tan $\delta$ : 0.05 max<br>IR : 1,000Mohm or 50Mohm $\times \mu\text{F}$<br>Whichever is smaller | With 200% of the rated voltage<br>Max. operating temperature<br>1,000+48/-0hrs  |
| Temperature Cycling              | Capacitance change : within $\pm 7.5\%$<br>Tan $\delta$ , IR : initial spec.   | 1 cycle condition<br>Min. operating temperature $\rightarrow 25^\circ\text{C}$<br>$\rightarrow$ Max. operating temperature $\rightarrow 25^\circ\text{C}$<br><br>5 cycle test |

※ The reliability test condition can be replaced by the corresponding accelerated test condition.

### D. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260 $\pm 5^\circ\text{C}$ , 30sec. )



Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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- ③ Medical equipment
- ④ Military equipment
- ⑤ Disaster prevention/crime prevention equipment
- ⑥ Power plant control equipment
- ⑦ Atomic energy-related equipment
- ⑧ Undersea equipment
- ⑨ Traffic signal equipment
- ⑩ Data-processing equipment
- ⑪ Electric heating apparatus, burning equipment
- ⑫ Safety equipment
- ⑬ Any other applications with the same as or similar complexity or reliability to the applications